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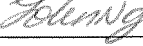
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status of the attached document

EXTERNAL ISSUE

Doc No.	SDSC-PSE-AN7164	Issue Level	Rev	Eff Date
		1	4	27-FEB-06
Doc Title	Product Specifications for AN7164	Total no. of pages (excluding this page)		8

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Structure	Silicon Monolithic Bipolar IC
Appearance	FP12S Plastic Package (Power Type with Fin attached)
Application	Stereo Set • Karaoke • TV
Function	Low Frequency Power Amplifier

A	Absolute Maximum Ratings				
No.	Item	Symbol	Ratings	Unit	Note
1	Storage Temperature	Tstg	-55 ~ +150	° C	1
2	Operating Ambient Temperature	Topr	-30 ~ +75	° C	1
3	Operating Ambient Pressure	Popr	$1.013 \times 10^5 \pm 0.61 \times 10^5$ (1.0 ± 0.6)	Pa (atm)	
4	Operating Constant Acceleration	Gopr	9,810 (1000)	m/s ² (G)	
5	Operating Shock	Sopr	4,900 (500)	m/s ² (G)	
6	Supply Voltage	Vcc	30	V	2
7	Supply Current	Icc	5.0	A	
8	Power Dissipation	P _D	62.5	W	$\theta_{j-c} = 2.0$ (°C/W)

Operating Supply Voltage Range	Vcc	8.3V ~ 24V
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Note 1) The temperature of all items shall be Ta=25°C except storage temperature and operating ambient temperature.

2) No signal.

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B Electrical Characteristics		(Unless otherwise specified, the ambient temperature is 25°C ± 2°C, Vcc=21V, RL=8Ω, freq=1kHz, BTL operation.)							
No	Item	Symbol	Test Circuit	Conditions	Limits			Unit	Note
					min	typ	max		
1	Quiescent Circuit Current	ICQ	1	Vin=0	-	55	100	mA	
2	Output Noise Voltage	Vno	1	Rg=10kΩ	-	0.85	1.3	mV	3
3	Output Offset Voltage	Voffset	1	Vin=0	-	0	300	mV	
4	Total Harmonic Distortion	THD	1	PO=1W	-	0.07	0.3	%	
5	Voltage Gain	Gv	1	PO=1W	49.5	51.5	53.5	dB	
6	Maximum Power Output	PO	1	THD=10%	24	30	-	W	
7	Ripple Rejection Ratio	R.R	1	Rg=0 Supply ripple	45	51	-	dB	3,4
8	Standby Current	ISTB	1	Pin 6 OPEN	-	-	3	μA	

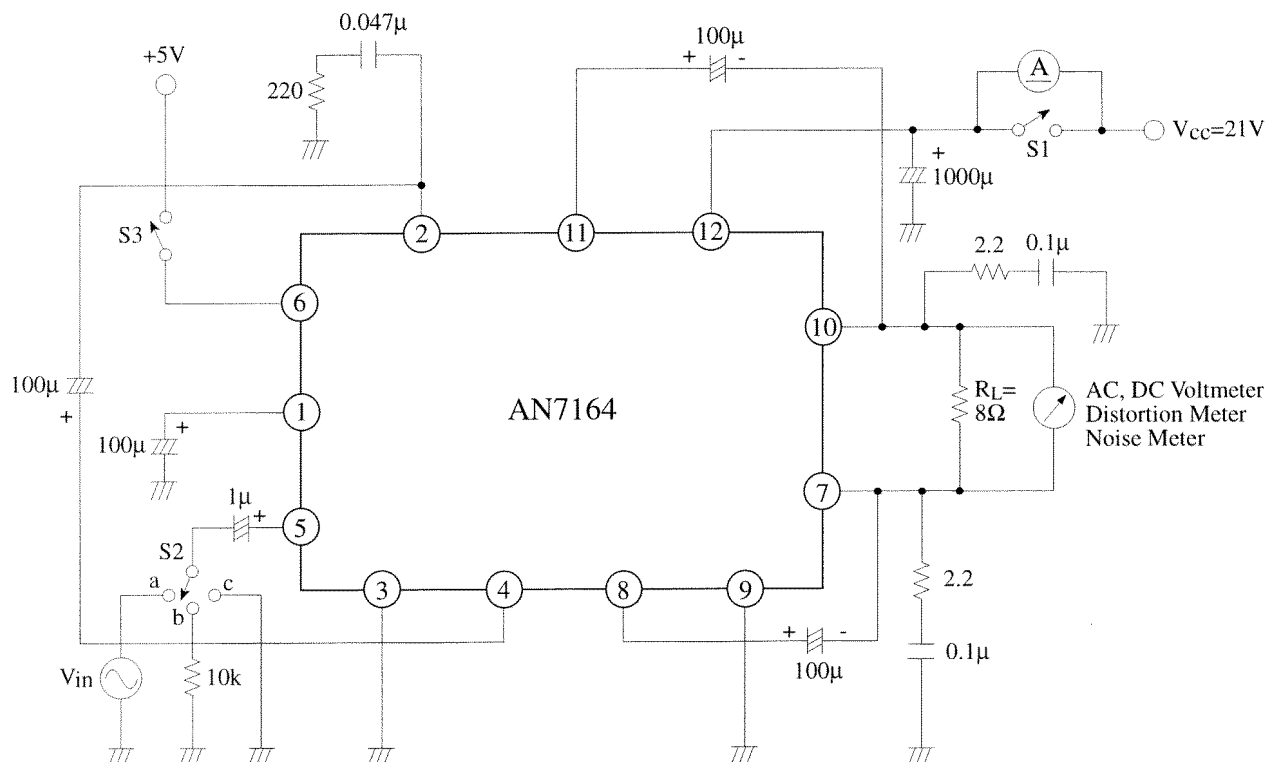
Note 3) Measure with DIN/Audio filter.

4) Ripple frequency = 120Hz, 1Vrms.

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(Description of test circuit and test method)

Test Circuit 1

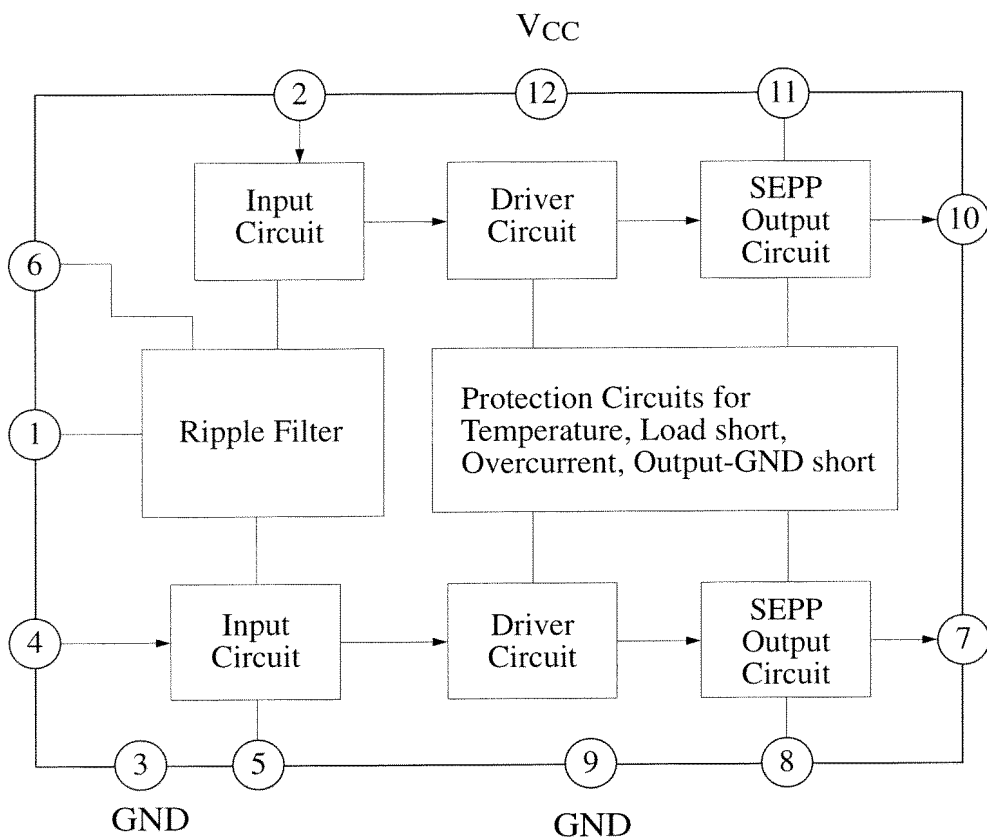


No.		S1	S2	S3
1	I _{cQ}	OFF	c	ON
2	V _{no}	ON	b	ON
3	V _{offset}	ON	c	ON
4	THD	ON	a	ON
5	G _v	ON	a	ON
6	P _o	ON	a	ON
7	R.R	ON	c	ON
8	I _{STB}	OFF	c	OFF

Note) Pin 6 is a stand-by pin.

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Circuit Function Block Diagram



Pin Descriptions

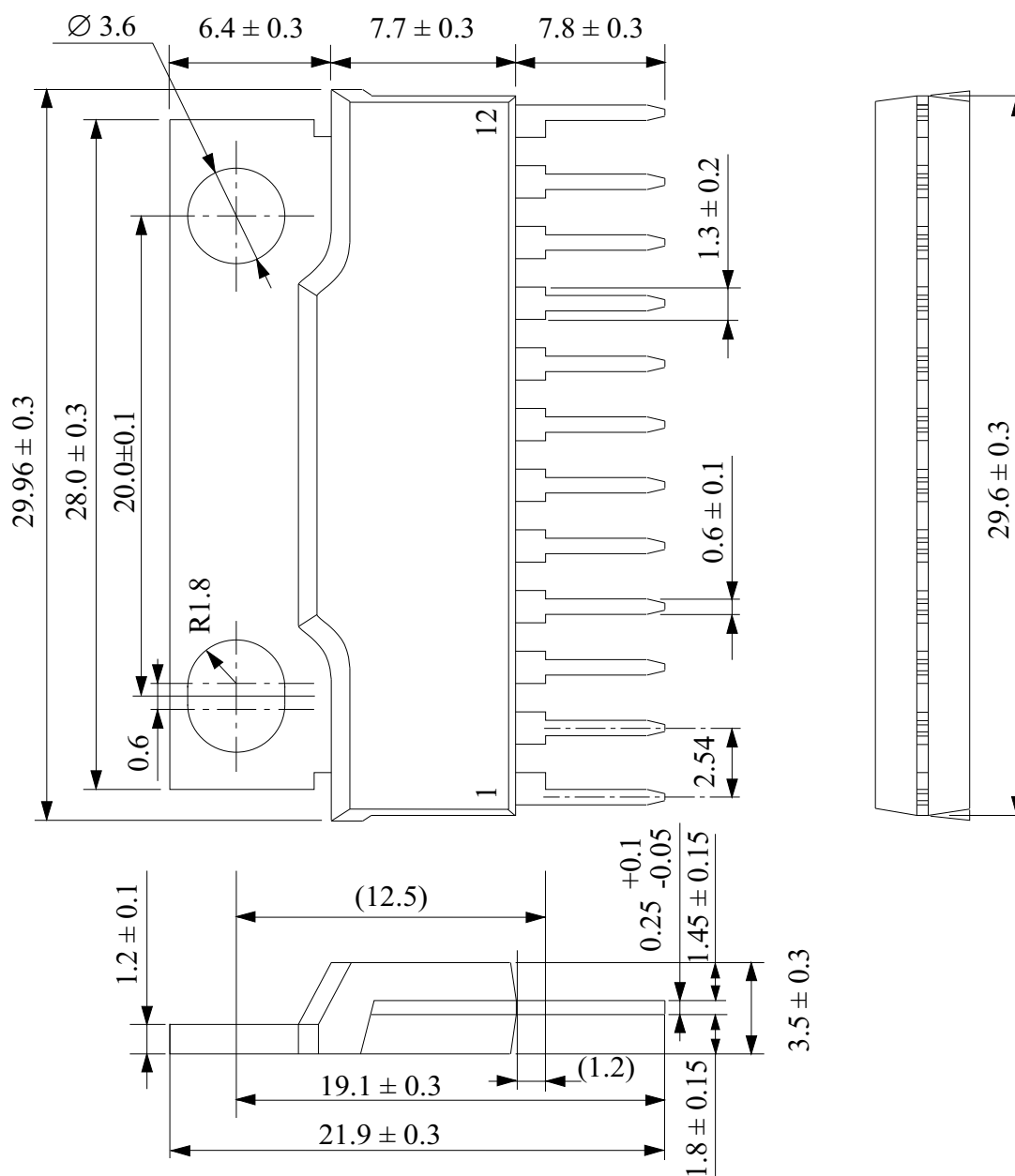
Pin No.	Description	Pin No.	Description
1	Ripple Filter	7	Output (Ch1)
2	Negative Feedback (Ch2)	8	Bootstrap (Ch1)
3	GND (Input)	9	GND (Output)
4	Negative Feedback (Ch1)	10	Output (Ch2)
5	Input	11	Bootstrap (Ch2)
6	Standby / Mute	12	Vcc

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Package Name FP12S

Unit : mm



() : Reference value

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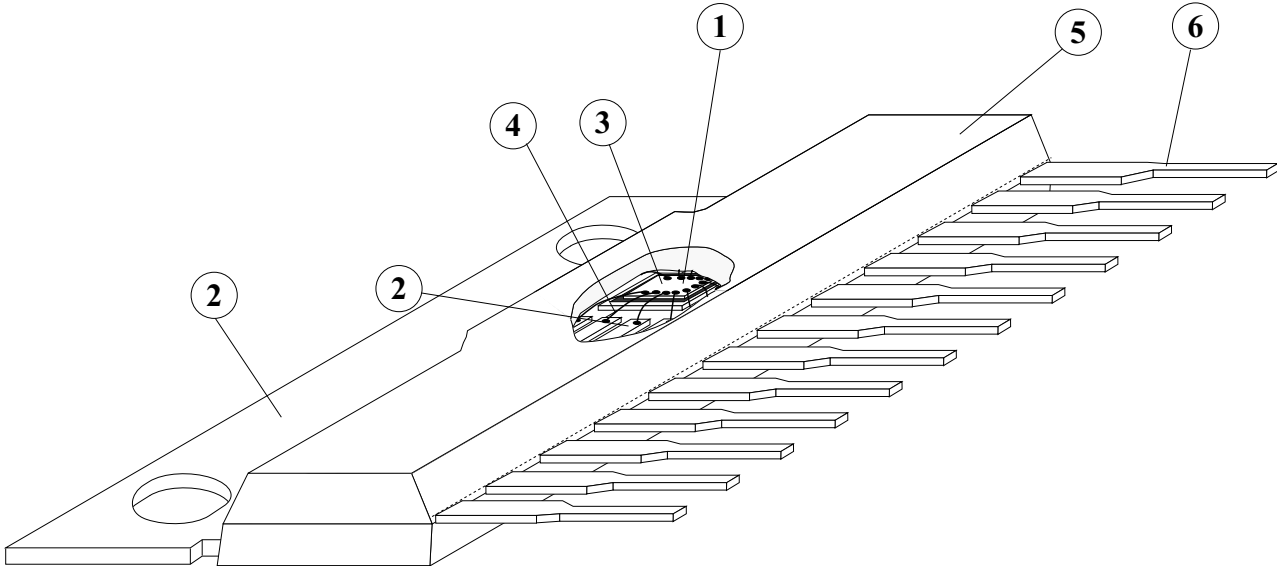
(Structure Description)

Chip surface passivation	SiN,	PSG,	Others ()	①
Lead frame material	Fe group,	Cu group,	Others ()	②, ⑥
Inner lead surface process	Ag plating,	Au plating,	Others ()	②
Outer lead surface process	General Customer: Solder Plating (98Sn-2Bi) SC Buyback: Solder Dip (95.5Sn-2Ag-2Bi-0.5Cu)			⑥
Chip mounting method	Ag paste,	Au-Si alloy,	Solder (95.5Pb-2.5Ag-2Sn)**,	③
Wire bonding method	Thermalsonic bonding,		Others ()	④
Wire material	Au,	Diameter <u>38</u> μm	Others ()	④
Mold material	Epoxy,	Others ()		⑤
Molding method	Transfer mold,	Multiplunger mold,	Others ()	⑤
Fin material	Cu group,	Others ()		⑦

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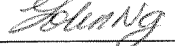
Package FP12S

** Under RoHS exemption clause, Lead (Pb) in high melting temperature type solder (ie. tin-lead solder alloy containing more than 85% of lead), is exempted until 2010.



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Product Specifications

(Technical Data)

AN7164

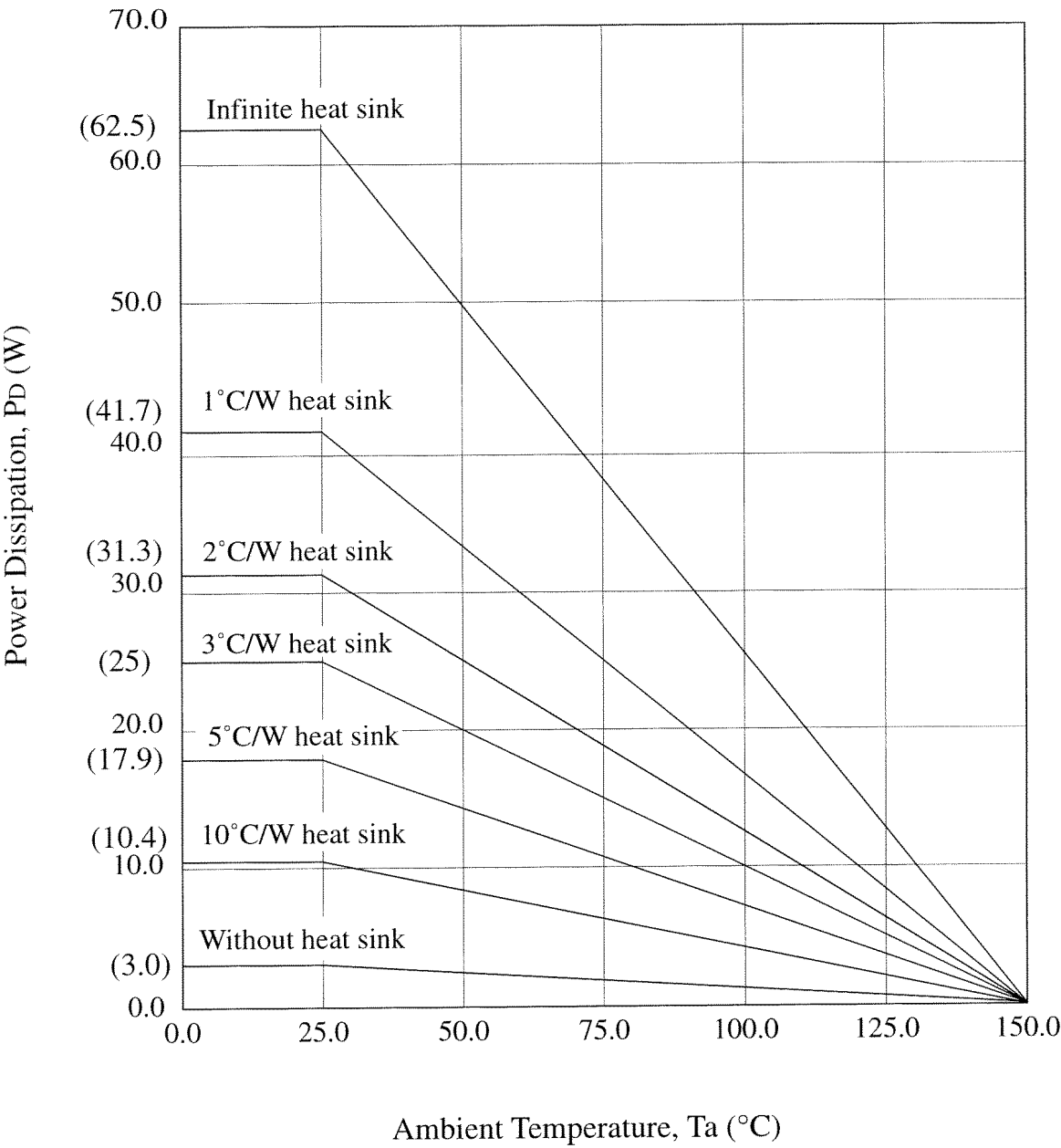
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FP-12S Package Power Dissipation

P_D - T_a

$R_{th(j-c)} = 2^{\circ}\text{C/W}$

$R_{th(j-a)} = 42^{\circ}\text{C/W}$

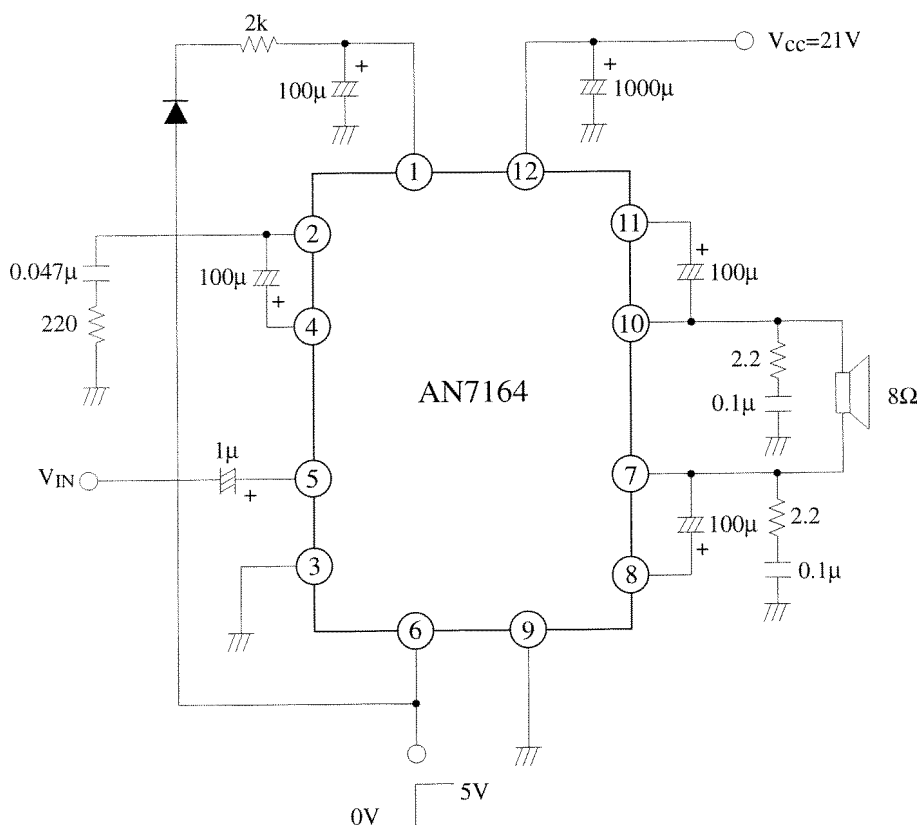


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(Precaution)

When standby is OFF (apply 5V at pin 6) at high temperature, the output disappears because ripple filter fast discharge circuit misoperates. It is necessary to force about 1mA of current into pin 1 when standby is OFF.
Below is one of the example for the application circuit.



Note) Please take note if the external circuit used is by following the test circuit, the standby function may misoperate and IC cannot function.

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